

- Priorities for placement:
1. Decoupling caps close to IC.
 2. J_VA12, J_VA19, J_VD12 close to IC.

Locate VIN_SE, TMST+, TMST- at edge opposite FMC connector

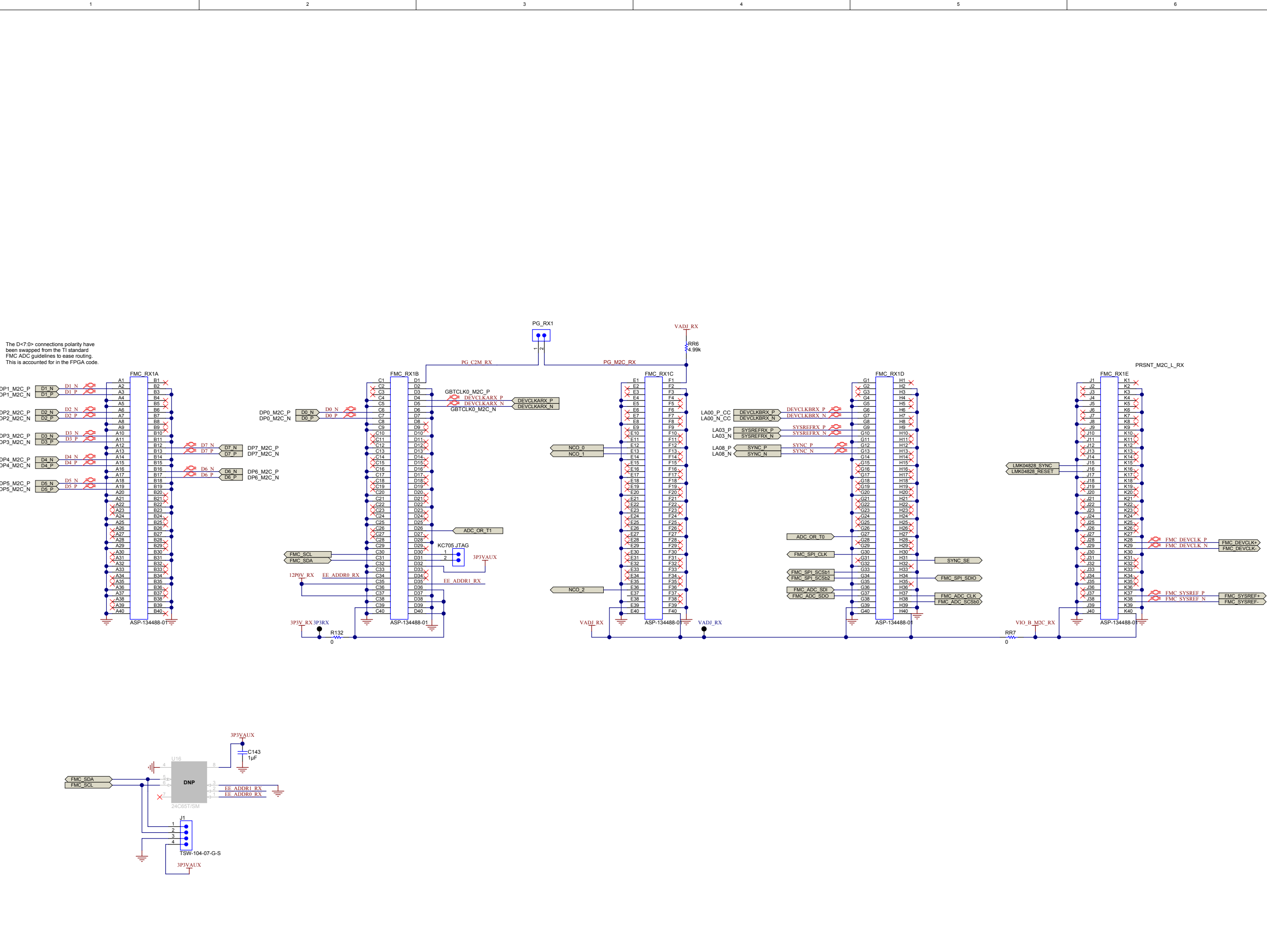
The IC pad is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground planes.

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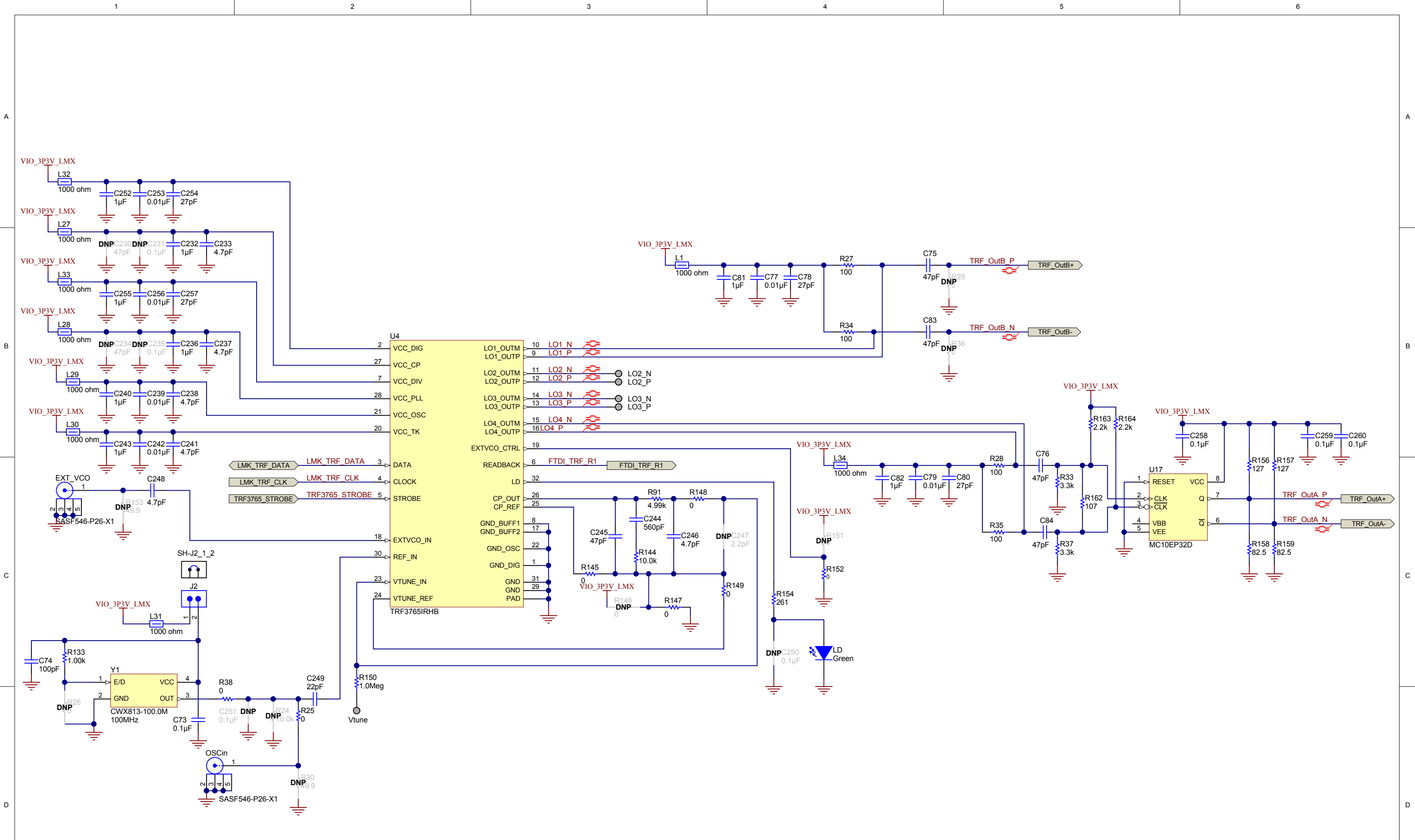
Number: TIDA-00431 Rev: A
 SVN Rev: Version control disabled
 Drawn By:
 Engineer: Jim Brinkhurst

Designed for: Internal Use Only Mod. Date: 12/8/2014
 Project Title: RF Sampling 4GSPS ADC with 8 GHz Amplifier
 Sheet Title:
 Assembly Variant: 001 TSW12J54EVM Sheet: 1 of 8
 File: TSW12J54EVM_A_1_ADC_IO.SchDoc Size: B
 Contact: <http://www.ti.com/support>




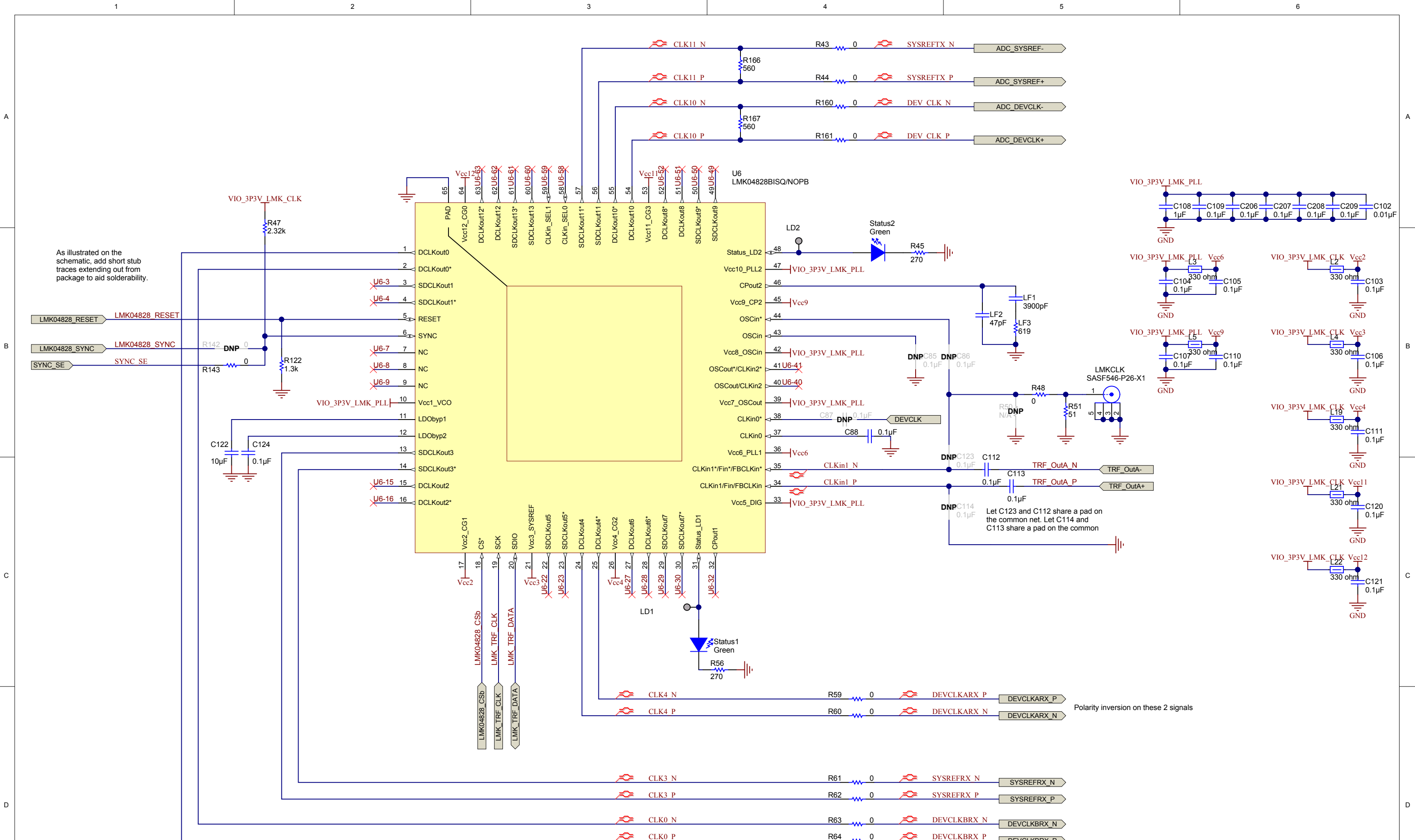


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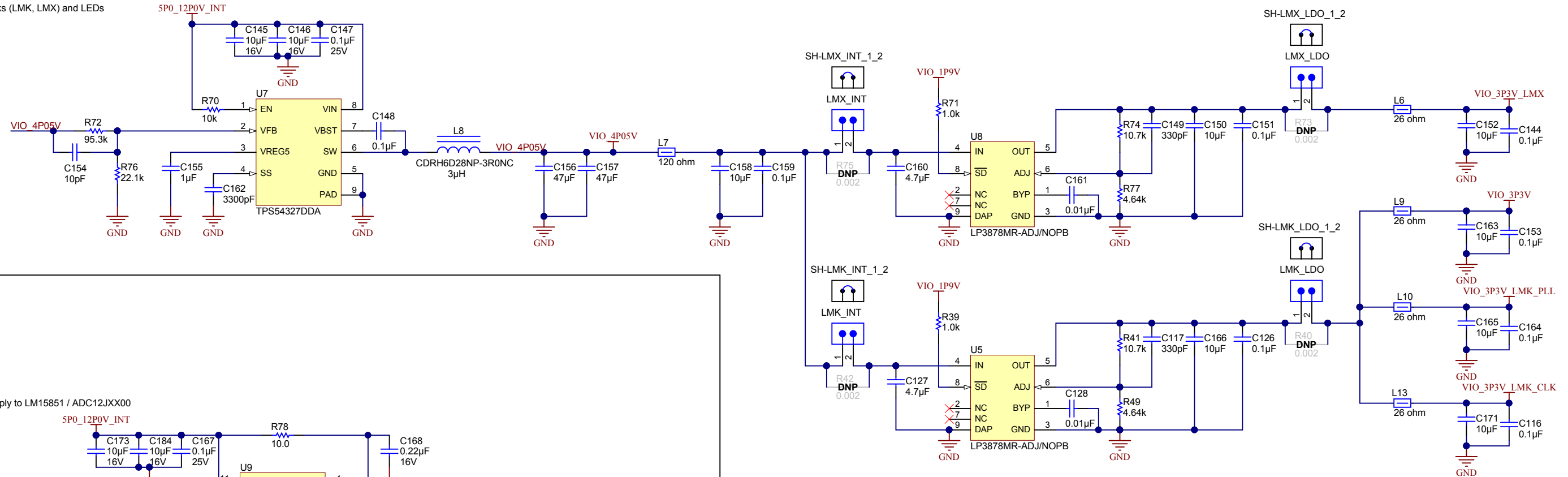
Designed for: Internal Use Only		Mod. Date: 12/17/2014	
Project Title: RF Sampling 4GSPS ADC with 8 GHz Amplifier			
Sheet Title: TRF3765			
Number: TIDA-00431	Rev: A	Assembly Variant: 001 TSW12J54EVM	
SVN Rev: Version control disabled		Sheet: 3 of 8	
Drawn By: Not shown in title block		File: TSW12J54EVM_A_3_TRF3765.SchDoc	
Engineer: Jim Brinkhurst		Size: B	
Contact: http://www.ti.com/support		 http://www.ti.com © Texas Instruments 2014	



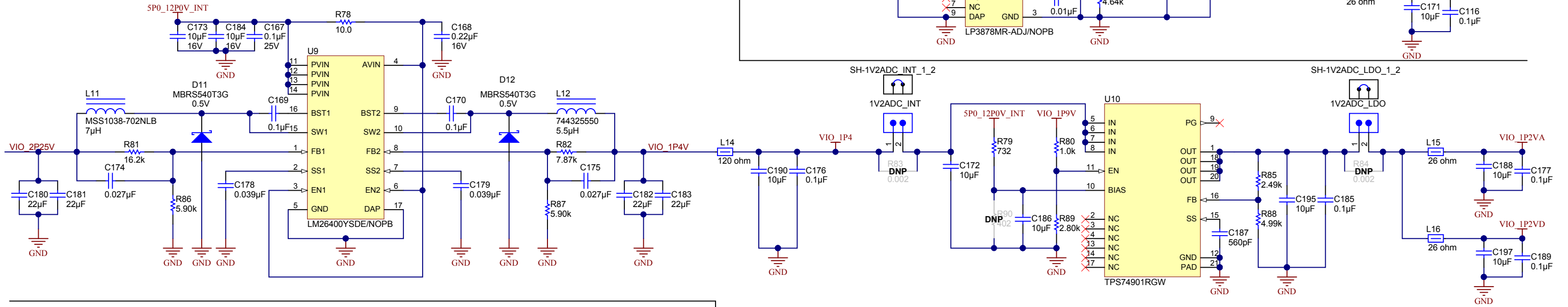
As illustrated on the schematic, add short stub traces extending out from package to aid solderability.

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3.3V supply to clocks (LMK, LMX) and LEDs

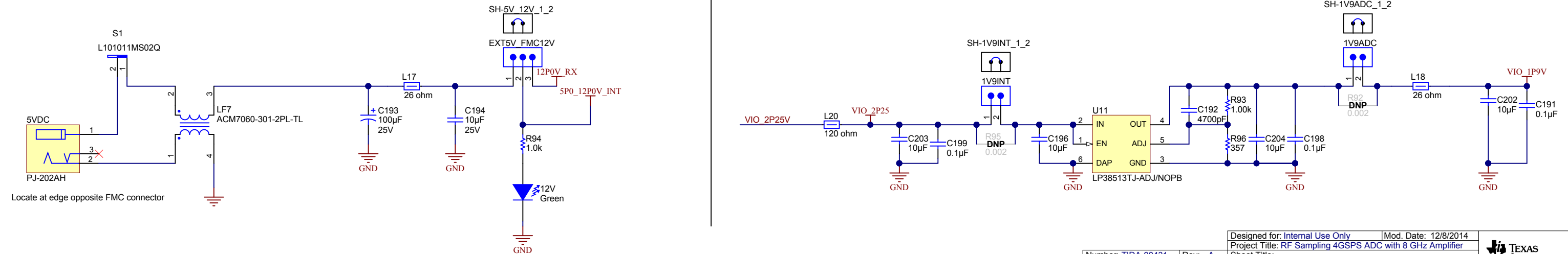


1.9V and 1.2V supply to LM15851 / ADC12JXX00



12V main supply, from jack or via FMC connector to regulators

Add text label: "5V VIA JACK" and "12V VIA FMC, Install R90 for 12V operation"

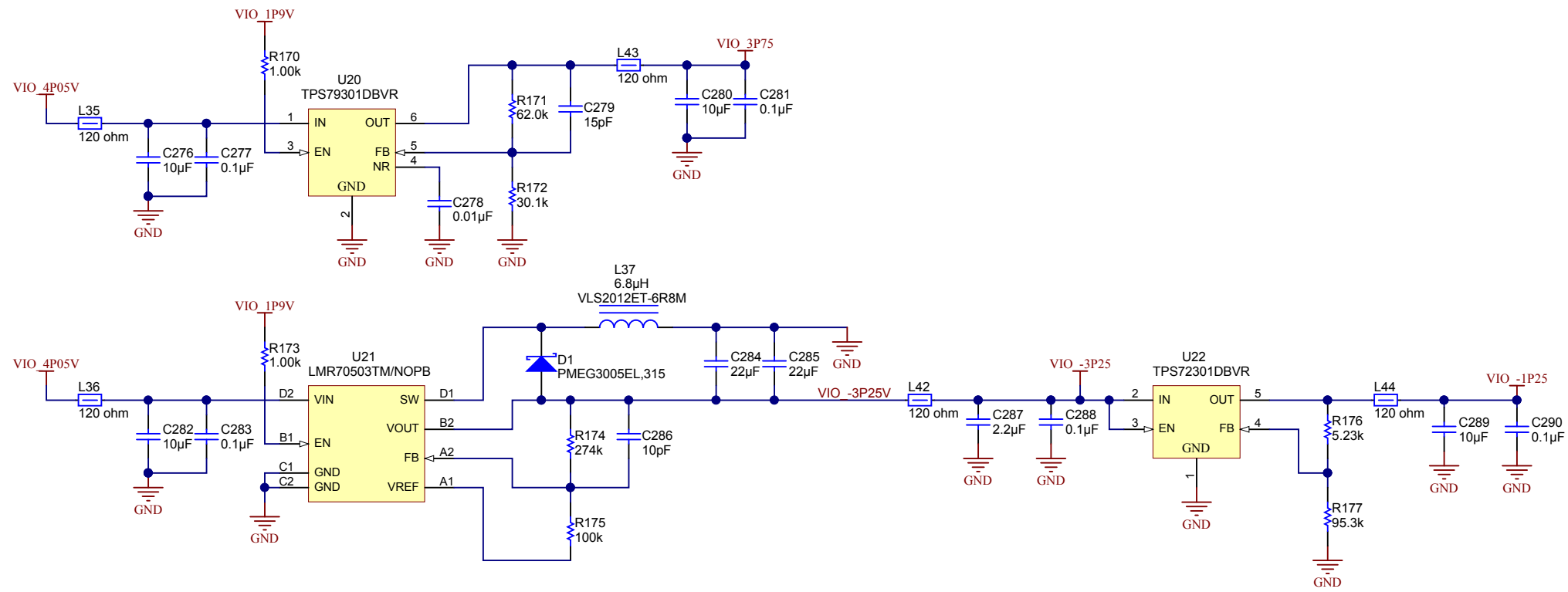


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Number: TIDA-00431	Rev: A	Mod. Date: 12/8/2014
Project Title: RF Sampling 4GSPS ADC with 8 GHz Amplifier		
Sheet Title:		
Assembly Variant: 001_TSW12J54EVM	Sheet: 5 of 8	
File: TSW12J54EVM_A_5_Power.SchDoc	Size: B	
Engineer: Jim Brinkhurst	Contact: http://www.ti.com/support	

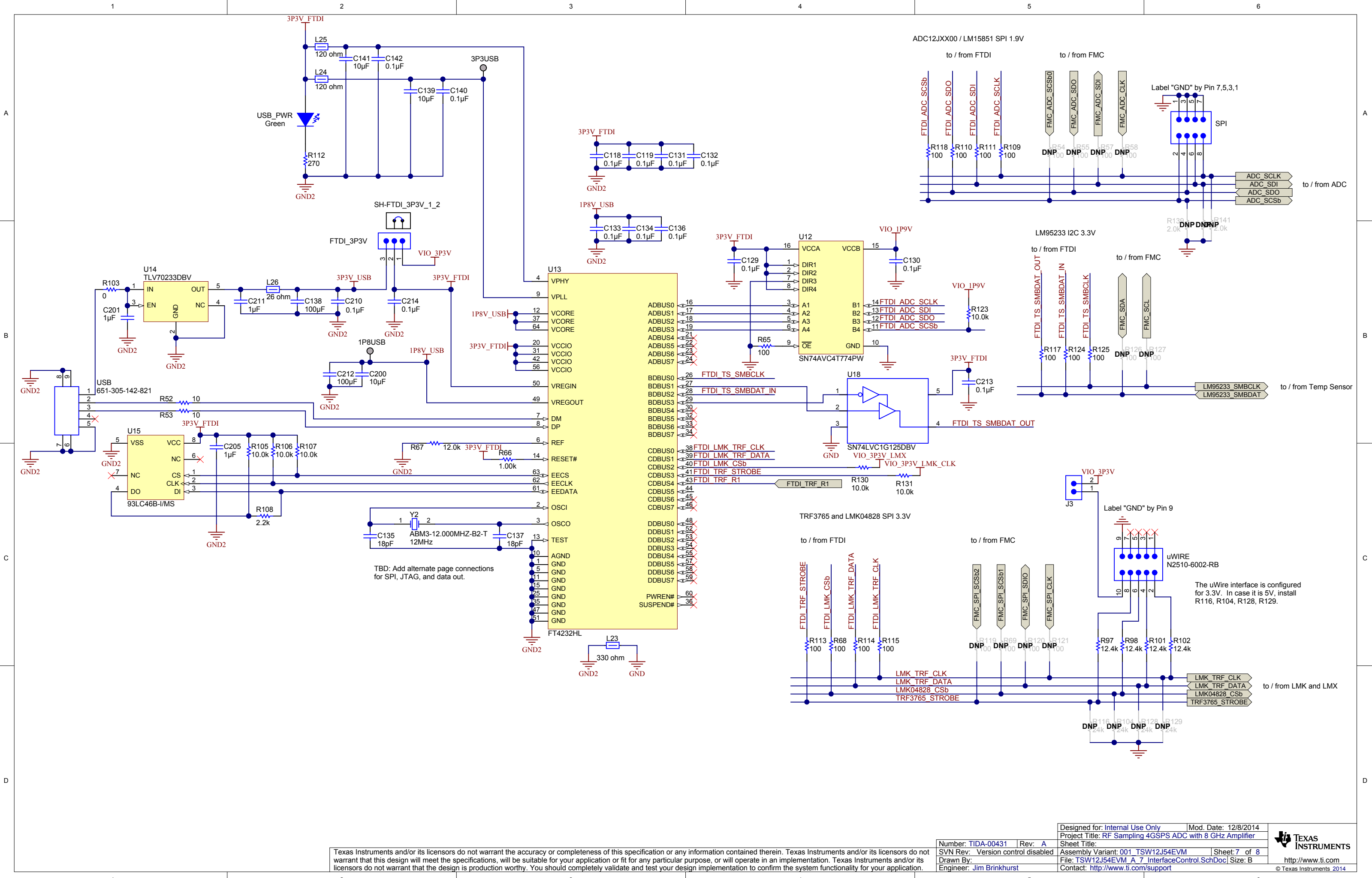


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Drawn By:		Sheet: 6 of 8	
Engineer: Jim Brinkhurst		File: TSW12J54EVM_A_6_Power.SchDoc	
		Size: B	
		Contact: http://www.ti.com/support	
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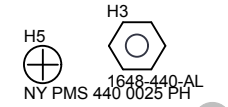
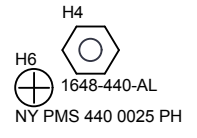
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DNP
FID1

PCB
ESD LOGO
ESD Susceptible

PCB Number: TIDA-00431
PCB Rev: A

PCB
LOGO
Texas Instruments



DNP
FID2

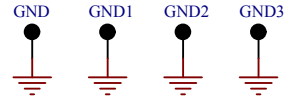
DNP
FID3

H9
MECH
FMC - FMC Screw
PMSSS 256 0075 PH

H10
MECH
FMC - FMC Nut

H11
MECH
FMC - FMC Screw
PMSSS 256 0075 PH

H12
MECH
FMC - FMC Nut



Place at least two of the GND test points in the power section.

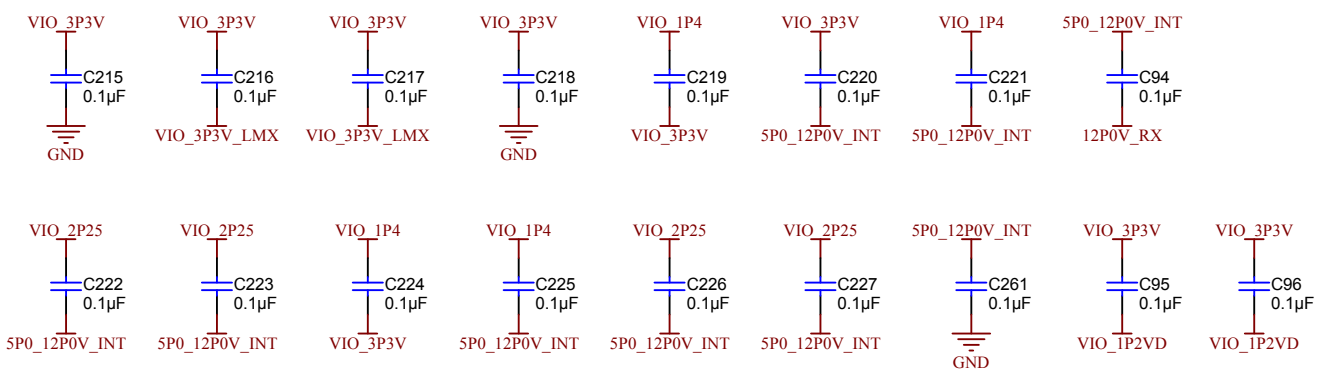
LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



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